

Product Name: ZX050C-DFN0808 (X2-DFN0808-4) Characterization testing bringup breakout module

Product Description: High Speed characterization module meeting 10GHz signal bandwidth with < 0.3dB insertion loss. Each pin of the device under test, U1, is accessible via 2 dedicated SMA connectors for external stimulus as well as measurement purpose.

ZX050C-DFN0808 is designed for ASIC (IC) characterization, functional testing of X2-DFN0808-4 packaged device. ZX50C-DFN0808 is designed with 50 Ω (Ohms) trace impedance using 4 layer PCB. The module includes 35μ gold plated SMA connectors.

Ideal evaluation, bringup, and testing of any discrete component such as ESD diode, sensor, or any IC using X2-DFN0808 footprint package.

Available Rxy to GND on each U1 pin (xy is the U1 pin number). Rxy is unpopulated 0402 SMD footprint. User may apply any standard 0402 device as required, resistor, capacitor, bead. . .

Available GND test point header pin interfacing with the module's GND plane & GND fills

Application: Bringup, Characterization, testing, development, modular design evaluations

Target DUT : Designed specifically for any DFN0808-4 (X2-DFN0808-4) SMD device with SMA connectors accessing all pins of the DFN0808-4

Pitch: Standard DFN0808-4 (X2-DFN0808-4) SMD package or equivalent

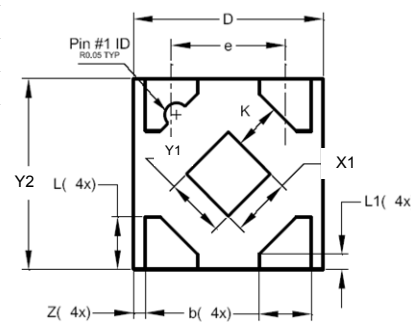
Headers: Ground access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height

DUT landing pads: Surface Mount, 4 pin package – DFN0808-4 (X2-DFN0808-4) or equivalent

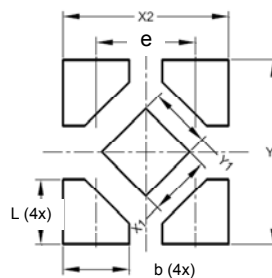
DFN0808-4 DIMENTIONS (mm)

UNIT		b	L	e	X1	Y1	X2	Y2
mm	max	0.2700	0.2700		0.300	0.300	0.800	0.90
	typical	0.2200	0.2200	0.480				
	min	0.1700	0.1700					

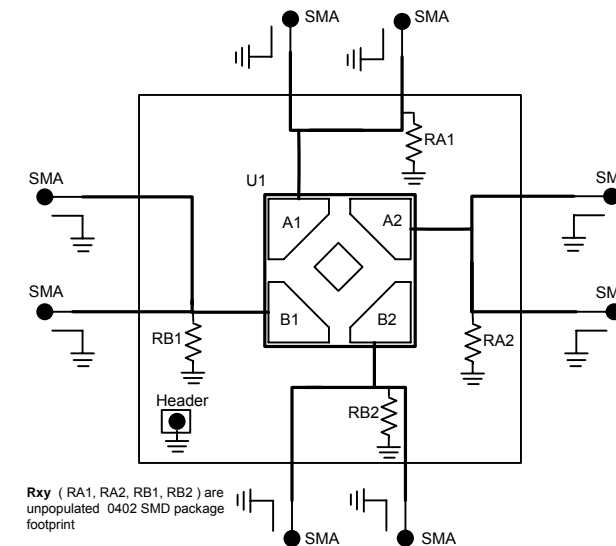
OUTLINE Version	REFERENCES		
	IEC	JEDEC	JEITA
X2-DFN0808-4			



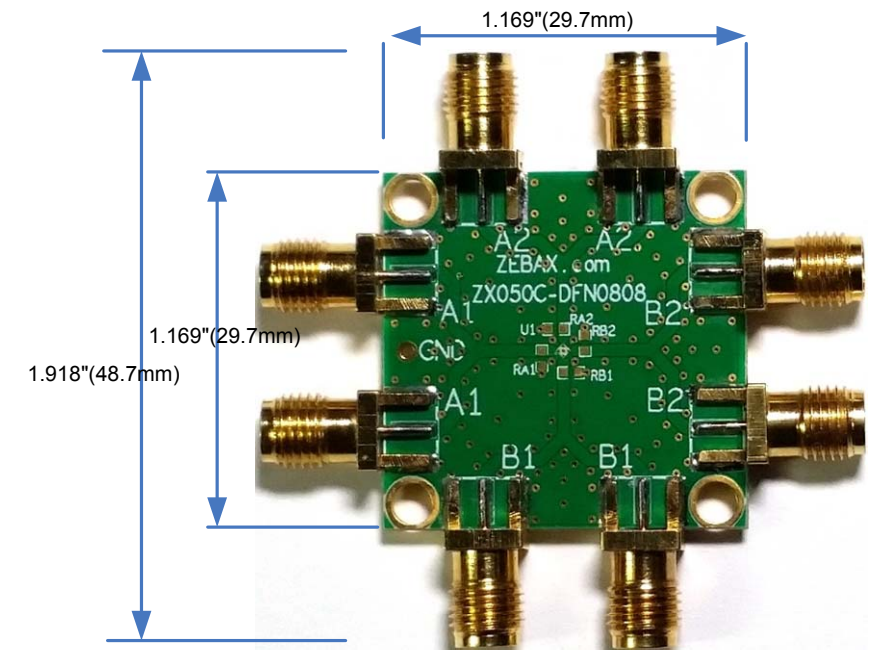
Pad Layout



Simplified Block Diagram:



Rxy (RA1, RA2, RB1, RB2) are unpopulated 0402 SMD package footprint



Ordering INFO:

Part Number
 ZX050C-DFN0808J SMA Jack Connector type (standard)
 ZX050C-DFN0808P SMA Plug connector type

NOTE: ZX050C-DFN0808 is shipped without DUT. All SMA connectors are installed.

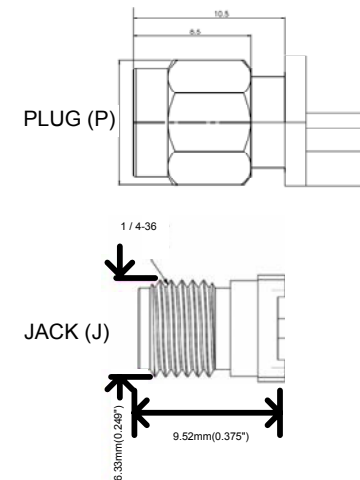
Note
 ALL ZEBAX products are RoHS compliant and Lead Free unless otherwise indicated.

SMA:
 Impedance: 50Ω
 Temp Range: -65°C +165°C
 Vibration: MIL-STD-202, Method 213
 Frequency Range: DC – 12GHz
 Working Voltage: 335V max
 Withstand Voltage: 1000V rms
 Center Contact: ≤3mΩ
 Outer Contact: ≤2mΩ
 Insulation resistance: ≥5000MΩ
 VSWR Straight: ≤1.15 (0.8-2.5G)

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SPECIFIED DIMENSIONS ARE INCHES (MM). ROHS COMPLIANT

ASSEMBLY DRAWING
ITEM: ZX050C-DFN0808

DESCRIPTION: DFN0808-4 (X2-DFN0808-4) characterization testing bringup breakout adapter SMA

CHECKED: M. MARINA	DRAWN: SLAVIK	REVISION: 1.0 SHEET: 1 OF 1
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